

NC601 Power Core Wire Solder

INTRODUCTION

NC601 Power Core Wire Solder is a RA activated No Clean for repairing through-hole, mixed and surface mount assemblies. The flux core provides faster and better fluxing activity than typical RA flux cores. NC601 flux is formulated to provide clear, colorless residues, maximum activity and high reliability without cleaning in most situations.

ATTRIBUTES

- Excellent cosmetics and a low, clear residue
- Superior activity offering good solderability on all surface finishes
- Excellent spread and wetting

APPLICATION

NC601 Power Core is suitable for use in any commercial hand soldering application. NC601 Power Core is ideal for difficult to solder metals such as brass, nickel and severely oxidized copper.

Solder iron temperature: 370 – 425C (700 – 800F)
Angle: hold the iron at 45 to 60 deg to the surface

NC601 is a no clean flux and the residues do not normally need to be removed. If removal of the flux is desirable, then the following cleaners have been tested and are effective at removal of the flux residues.

FCT Assembly: RA2000, SC101
Kyzen Aquanox: A4625, A4241, A4651US
Kyzen Cybersolv: 141-R
Kyzen Ionox: I3302

AVAILABILITY

NC601 Power Core Wire Solder is available in SN100C, SAC305 and Sn63/Pb37 alloys with diameters ranging from 0.015" to 0.125". The flux content varies from 2 to 3% by wt. depending upon the alloy.

TEST RESULTS

Properties	Values
Alloy	SN100C, SAC305, Sn63/Pb37
Flux Content	2 to 3% by wt.
Spread Factor	Over 90
Color	Clear, colorless flux
Copper mirror	Low activity
Halide Content	0.4%
Silver chromate	Halides present
Fluoride test	None detected
Ion chromatography	Halides detected
Flux class (J-STD-004)	ROL1

SAFETY AND HANDLING

Refer to the Material Safety Data Sheet for further information.

Store in a cool dry place.